PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT4928294

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
KUNIHIKO KONDO	03/26/2018
KAZUHIRO OHTAKI	03/26/2018
YUJI MINOWA	03/26/2018
TOSHINARI TAKEYAMA	03/30/2018
TOSHIO KAGITANI	03/30/2018

RECEIVING PARTY DATA

YACHIYO INDUSTRY CO., LTD.
393 KASHIWABARA, SAYAMA-SHI,
SAITAMA
JAPAN
3501335
THE JAPAN STEEL WORKS, LTD.
11-1 OSAKI 1-CHOME
SHINAGAWA-KU
TOKYO
JAPAN
141-0032

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15770216

CORRESPONDENCE DATA

Fax Number: (202)748-5915

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 202-748-5902

Email: tsato@kviplaw.com, ip@kviplaw.com

Correspondent Name: KENEALY VAIDYA LLP Address Line 1: 3000 K STREET, N.W.

Address Line 2: SUITE 200

Address Line 4: WASHINGTON, D.C. 20007

504881553 PATENT REEL: 045614 FRAME: 0267

ATTORNEY DOCKET NUMBER:	5096-0035
NAME OF SUBMITTER:	DAVID J. KENEALY
SIGNATURE:	/david j. kenealy/
DATE SIGNED:	04/23/2018

Total Attachments: 4

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> PATENT REEL: 045614 FRAME: 0268

ASSIGNMENT

WHEREAS WE, the below named inventors, [hereinafter referred to as Assignors], have made an invention entitled:

PARISON GUIDE

for which WE filed PCT Application No. PCT/JP2016/080023 on October 7, 2016 and for which WE executed an application for United States Letters Patent concurrently herewith; and

WHEREAS YACHIYO INDUSTRY CO., LTD., a corporation of Japan, whose post office address is 393
Kashiwabara, Sayama-shi, Saitama 350-1335, JAPAN and THE JAPAN STEEL WORKS, LTD. a corporation of Japan, whose post office address is 11-1 Osaki 1-chome, Shinagawa-ku, Tokyo 141-0032, JAPAN (hereinafter collectively referred to as Assignee), are desirous of jointly and equally securing and sharing the entire right, title, and interest in and to this invention in all countries throughout the world in equal and joint portion, and in and to the application of United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that, for and in consideration of the sum of One Dollar (\$1.00) in hand paid and other good and valuable consideration the receipt of which from Assignee is hereby acknowledged, WE, as assignors, have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the Assignee, its lawful successors and assigns, OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof, and all rights to claim priority on the basis of such applications, and all applications for Letters Patent which may hereafter be filed for this invention in any foreign country and all Letters Patent which may be granted on this invention in any foreign country, and all extensions, renewals, and reissues thereof; and WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States and any official of any foreign country whose duty it is to issue patents on applications as described above, to issue all Letters Patent of this invention to Assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, WE HEREBY covenant that WE have the full right to convey the interest assigned by this Assignment, and WE have not executed and will not execute any agreement in conflict with this Assignment;

AND, WE HEREBY further covenant and agree that WE will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to US respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors or assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns;

AND, WE HEREBY authorize and request the attorneys WE have empowered in the Declaration and Power of Attorney in this application, to insert here in parentheses (Application No. 15/770,216 , filed April 23 , 2018) the filing date and application number of said application when known.

IN TESTIMONY WHEREOF, I have hereunto set my hand.

Full Name of First Assignor Kunihiko KONDO	Assignor's Signature Kunihiko Kondo	Date March 26, 2018
Address: c/o YACHIYO INDUSTRY CO., LTD., Saitama R&D Center, 2-11, Hirosedai 2-chome, Sayama-shi, Saitama 350-1328, JAPAN		<u>Citizenship</u> Japan
Names of additional inventors attached [X] Yes [] No		

KENEALY VAIDYA LLP

Full Name of Second Assignor Kazuhiro OHTAKI	Assignor's Signature Kazuhiro OH7AK	Date March 26. 20/P
Address: c/o YACHIYO INDUSTRY CO., LTD., Saitama R&D Center, 2-11, Hirosedai 2-chome, Sayama-shi, Saitama 350-1328, JAPAN		<u>Citizenship</u> : Japan
Full Name of Third Assignor Yuji MINOWA	Assignor's Signature Justi Minoua	Date March 26, 2018
Address: c/o YACHIYO INDUSTRY CO., LTD., Saitama R&D Center, 2-11, Hirosedai 2-chome, Sayama-shi, Saitama 350-1328, JAPAN		<u>Citizenship:</u> Japan
Full Name of Fourth Assignor Toshinari TAKEYAMA	Assignor's Signature	<u>Date</u>
Address: c/o Yokohama Plant, THE JAPAN STEEL WORKS, LTD., 2-1, Fukuura 2-chome, Kanazawa-ku, Yokohama-shi, Kanagawa 236-0004, JAPAN		<u>Citizenship</u> : Japan
Full Name of Fifth Assignor Toshio KAGITANI	Assignor's Signature	<u>Date</u>
Address: c/o Yokohama Plant, THE JAPAN STEEL WORKS, LTD., 2-1, Fukuura 2-chome, Kanazawa-ku, Yokohama-shi, Kanagawa 236-0004, JAPAN		<u>Citizenship</u> : Japan
Names of additional inventors attached [] Yes [X] No		[X] No

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WHEREAS WE, the below named inventors, [hereinafter referred to as Assignors], have made an invention entitled:

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for which WE filed PCT Application No. PCT/JP2016/080023 on October 7, 2016 and for which WE executed an application for United States Letters Patent concurrently herewith; and

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NOW THEREFORE, be it known that, for and in consideration of the sum of One Dollar (\$1.00) in hand paid and other good and valuable consideration the receipt of which from Assignee is hereby acknowledged, WE, as assignors, have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the Assignee, its lawful successors and assigns, OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof, and all rights to claim priority on the basis of such applications, and all applications for Letters Patent which may hereafter be filed for this invention in any foreign country and all Letters Patent which may be granted on this invention in any foreign country, and all extensions, renewals, and reissues thereof; and WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States and any official of any foreign country whose duty it is to issue patents on applications as described above, to issue all Letters Patent of this invention to Assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, WE HEREBY covenant that WE have the full right to convey the interest assigned by this Assignment, and WE have not executed and will not execute any agreement in conflict with this Assignment;

AND, WE HEREBY further covenant and agree that WE will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to US respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors or assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns;

AND, WE HEREBY authorize and request the attorneys WE have empowered in the Declaration and Power of Attorney in this application, to insert here in parentheses (Application No. 15/770,216 , filed April 23, 2018) the filing date and application number of said application when known.

IN TESTIMONY WHEREOF, I have hereunto set my hand.

Full Name of First Assignor Kunihiko KONDO	Assignor's Signature Kunihi ko Kondo	Date March 26, 2018
Address: c/o YACHIYO INDUSTRY CO., LTD., Saitama R&D Center, 2-11, Hirosedai 2-chome, Sayama-shi, Saitama 350-1328, JAPAN		<u>Citizenship</u> Japan
Names of additional inventors attached [X] Yes [] No		

Full Name of Second Assignor Kazuhiro OHTAKI	Assignor's Signature	Date
Address: c/o YACHIYO INDUSTRY CO., LTD., Saitama R&D Center, 2-11, Hirosedai 2-chome, Sayama-shi, Saitama 350-1328, JAPAN		<u>Citizenship</u> : Japan
Full Name of Third Assignor Yuji MINOWA	Assignor's Signature	<u>Date</u>
Address: c/o YACHIYO INDUSTRY CO., LTD., Saitama R&D Center, 2-11, Hirosedai 2-chome, Sayama-shi, Saitama 350-1328, JAPAN		<u>Citizenship</u> : Japan
Full Name of Fourth Assignor Toshinari TAKEYAMA	Assignor's Signature 竹山俊成	Date March 30,218
Address: c/o Yokohama Plant, THE JAPAN STEEL WORKS, LTD., 2-1, Fukuura 2-chome, Kanazawa-ku, Yokohama-shi, Kanagawa 236-0004, JAPAN		Citizenship: Japan
Full Name of Fifth Assignor Toshio KAGITANI	Assignor's Signature 描述 Tix 安 夫	Date March 20, 20/8
Address: c/o Yokohama Plant, THE JAPAN STEEL WORKS, LTD., 2-1, Fukuura 2-chome, Kanazawa-ku, Yokohama-shi, Kanagawa 236-0004, JAPAN		<u>Citizenship</u> : Japan
Names of additional inventors attached [] Yes [X] No		

KENEALY VAIDYA LLP

PATENT REEL: 045614 FRAME: 0272